

Back to basics: the onset of skin effect in circuit board traces

Eric Bogatin, Teledyne LeCroy Signal Integrity Academy
eric@beTheSignal.com

Yuriy Shlepnev, Simberian Inc.
shlepnev@simberian.com

Chun-Ting “Tim” Wang Lee, University of Colorado
Chunting.wanglee@colorado.edu

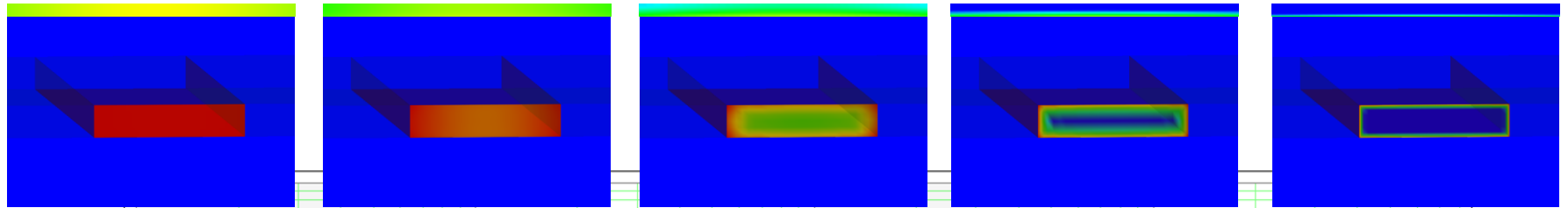


Agenda

- Skin effect in stripline environment
- Matching measurement of skin effect to simulation
 - Experiment setup
 - Measurement
 - Simulation
- Summary

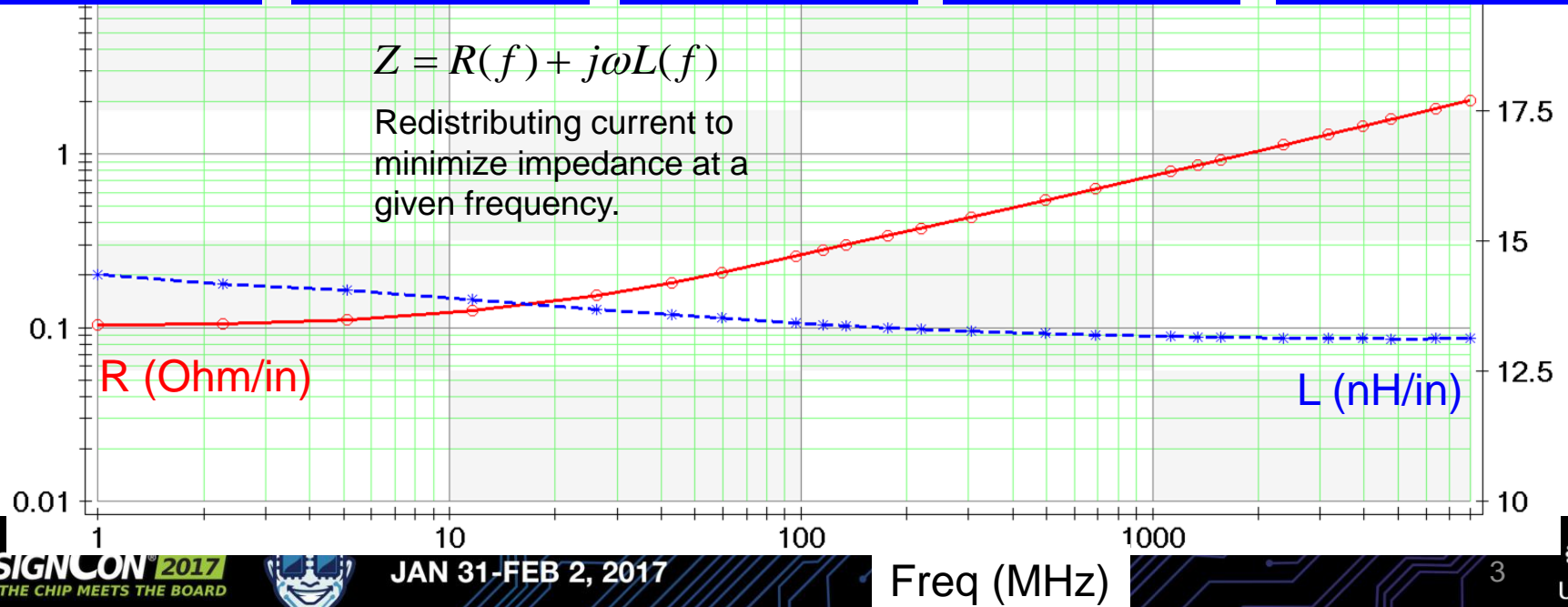


The Skin effect and $R_{Len}(f)$, $L_{Len}(f)$ in stripline



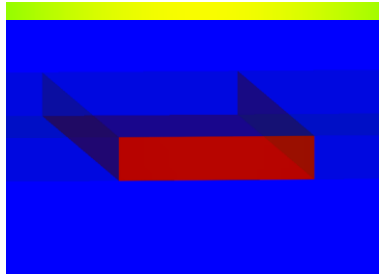
$$Z = R(f) + j\omega L(f)$$

Redistributing current to minimize impedance at a given frequency.

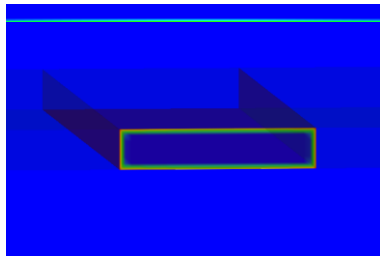


How do we match measured skin effect to simulation?

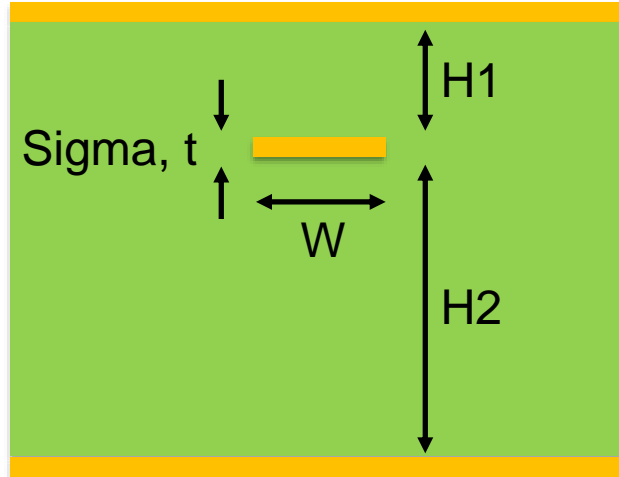
1 MHz



8 GHz



- It comes down to matching $R_{Len}(f)$ and $L_{Len}(f)$
- What are the trace parameters that affect $R_{Len}(f)$ and $L_{Len}(f)$?



Expect to affect $R_{Len}(f)$ to first order

- Width of trace
- Thickness of trace
- Conductivity of copper

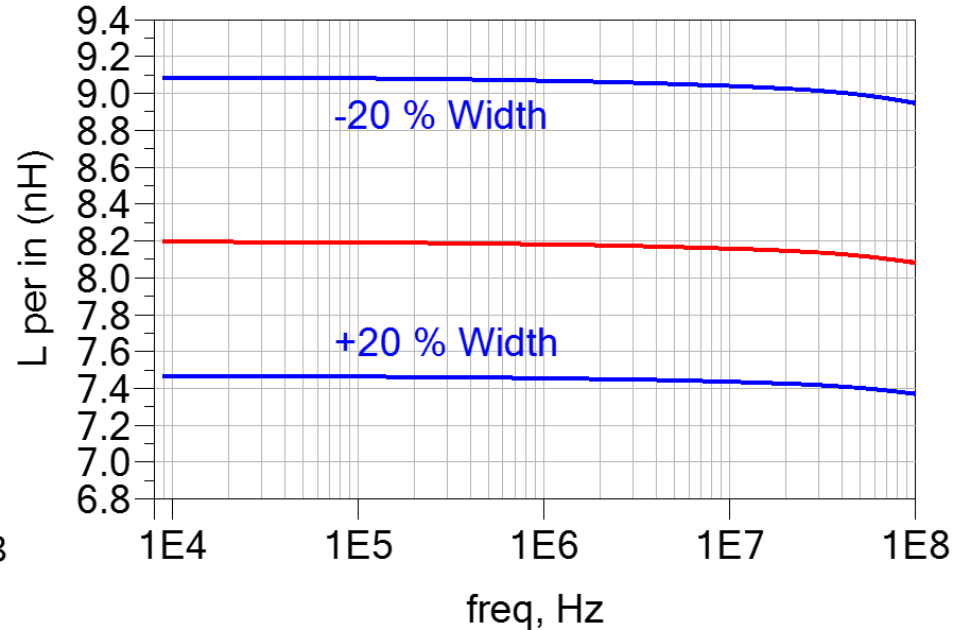
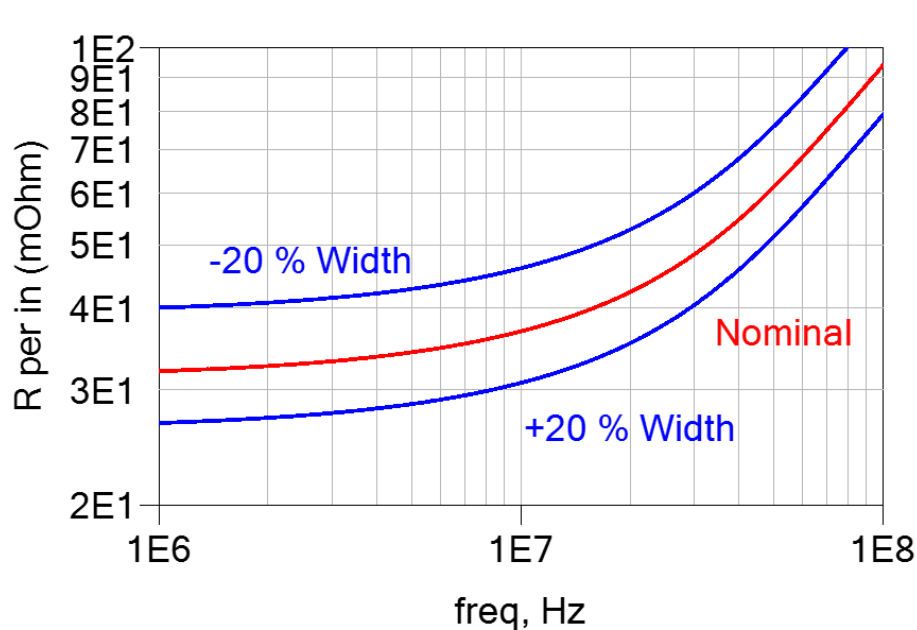
Expect to affect $L_{Len}(f)$ to first order

- Width of trace
- Substrate height



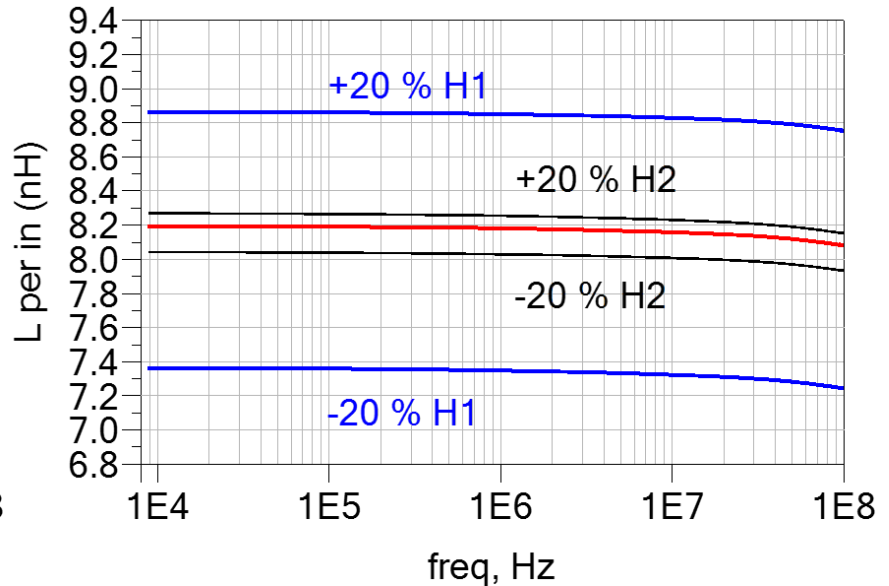
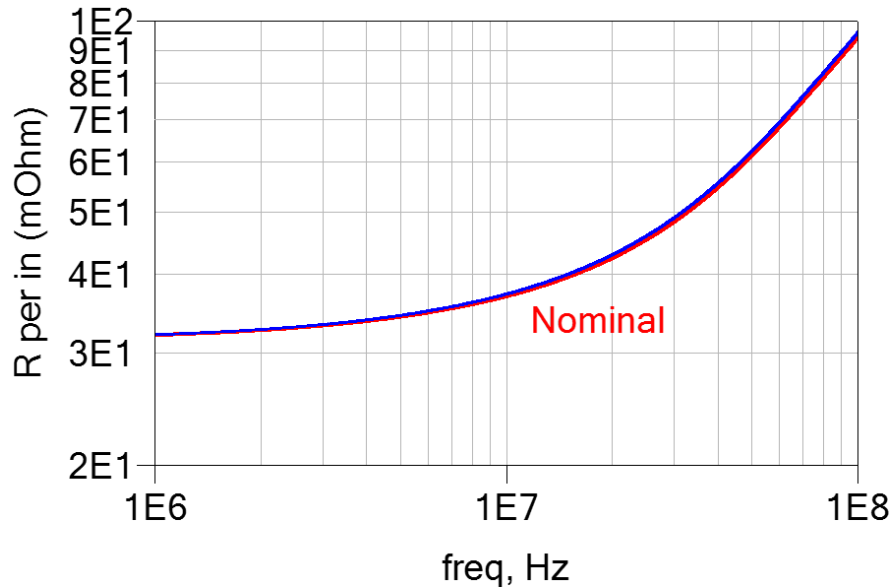
Sensitivity of $R_{Len}(f)$ and $L_{Len}(f)$ to W

Both curves are sensitive to width change.
Need to extract the fabricated trace width.



Sensitivity of $R_{Len}(f)$ and $L_{Len}(f)$ to H1, H2

To first order, $R_{Len}(f)$ is not sensitive to H changes, and $L_{Len}(f)$ most influenced by H1.

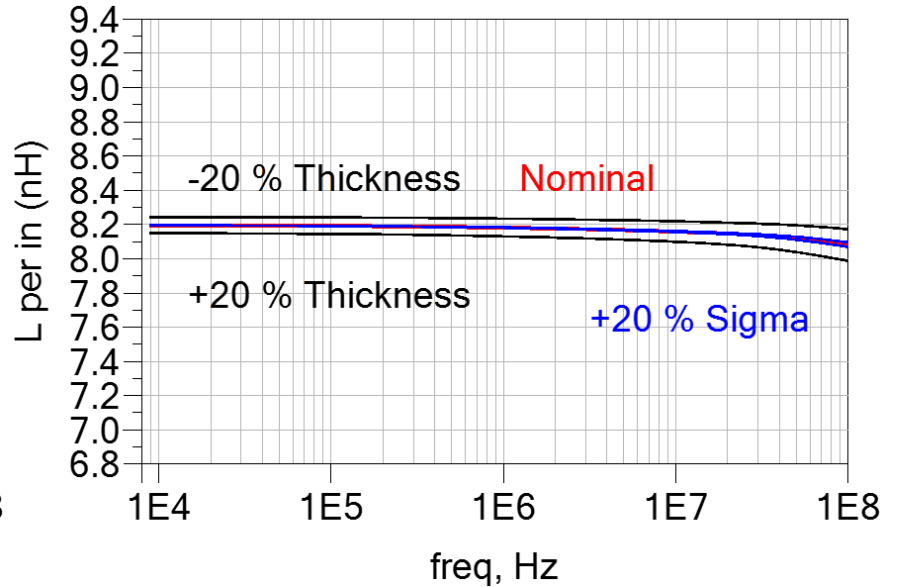
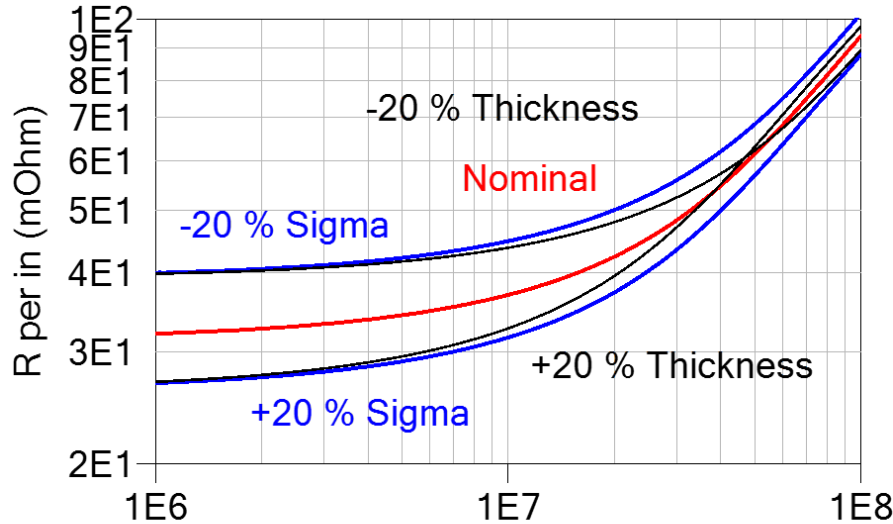


*less than 3% change from 20% H2 change



Sensitivity of $R_{Len}(f)$ and $L_{Len}(f)$ to Sigma and T

$R_{Len}(f)$ is sensitive to sigma and t change, but $L_{Len}(f)$ is insensitive to sigma.



At DC, $R_{Len} = \frac{1}{w\sigma t}$ freq, Hz

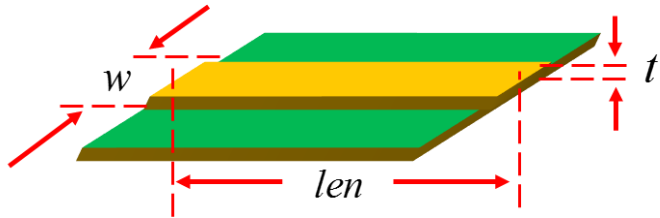
*less than 3% change from 20% Thickness change



Reducing number of variables: divide and conquer

Variables: W, Sigma, T and H1.

Is there a way to reduce the number of variable?

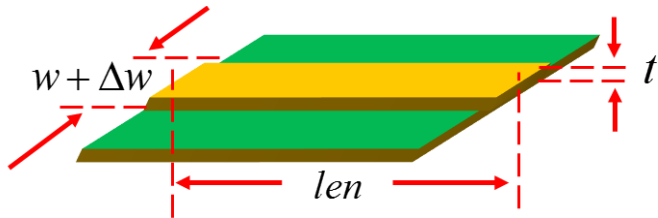


$$R = \frac{1}{\sigma} \frac{len}{w \cdot t} = \frac{1}{\sigma t} \frac{len}{w} = R_{\square} \cdot \frac{len}{w} = R_{\square} \cdot n$$

Rule of thumb:

Rsheet = 0.5 mOhm/sq for 1 oz copper

Rsheet = 1 mOhm/sq for 1/2 oz copper



Measure R_{sheet} and delta w, but how?

$$R = R_{\square} \cdot \frac{len}{w + \Delta w}$$

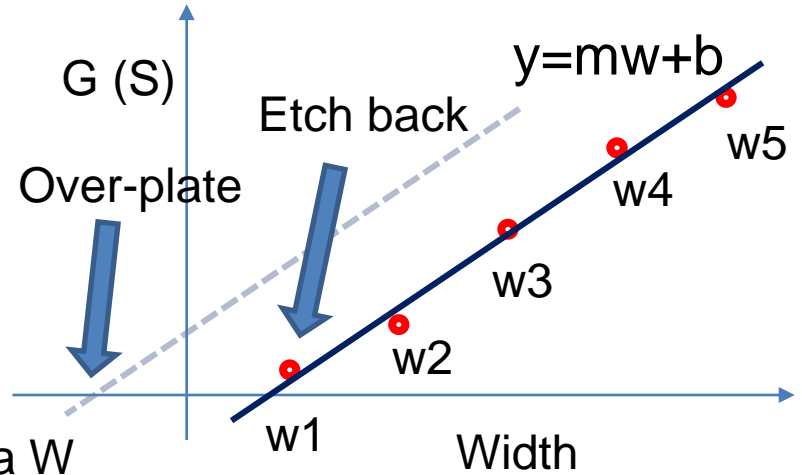
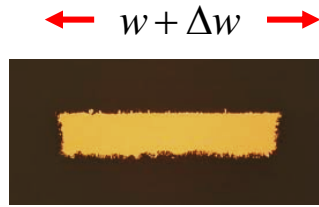


New technique to extract delta width and sheet resistance

Assume rectangular cross-section

$$R = R_{\square} \cdot \frac{\text{len}}{w + \Delta w}$$

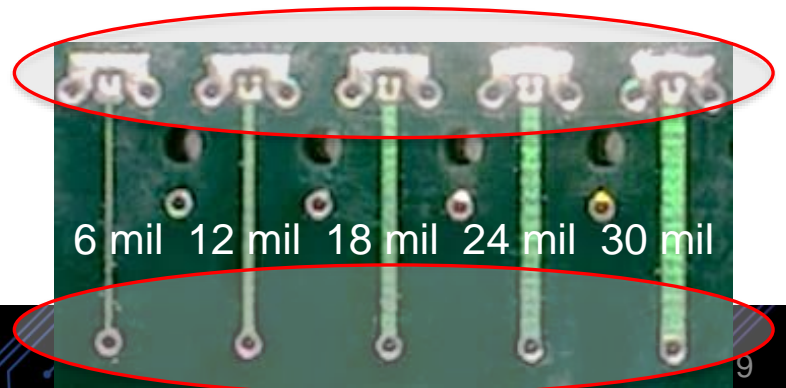
R_{\square} = sheet resistance, Δw = etchback/overplate



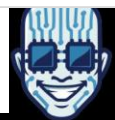
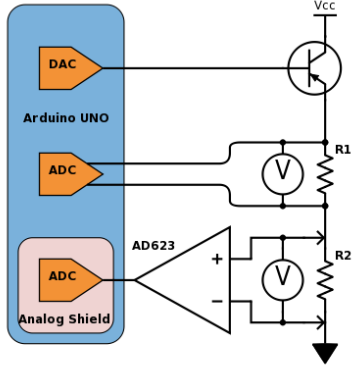
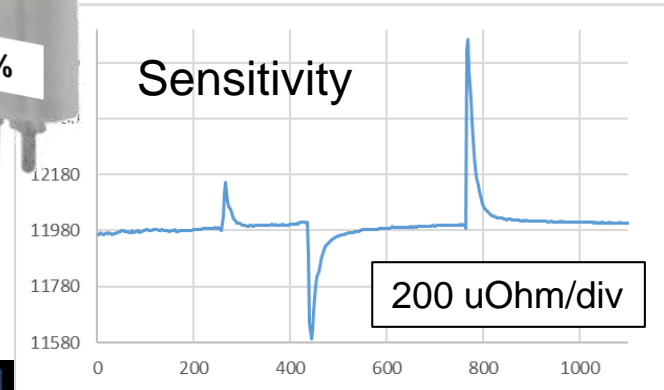
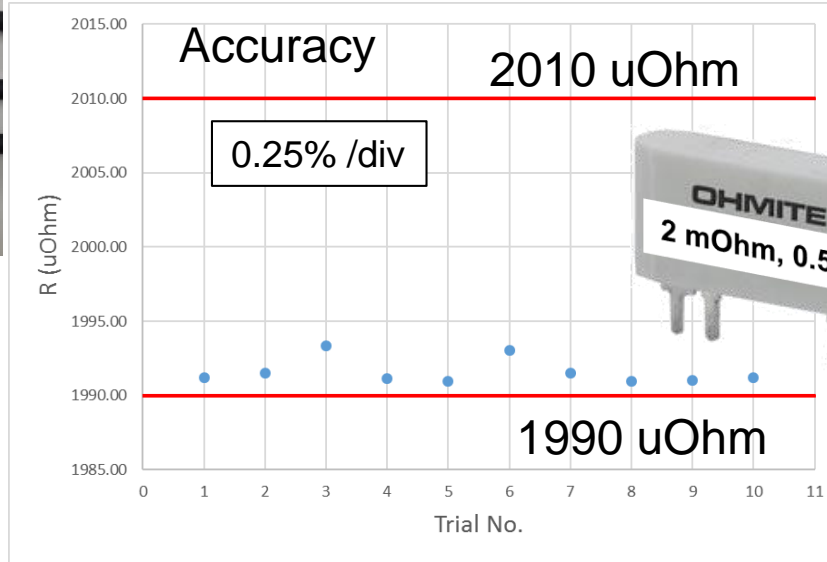
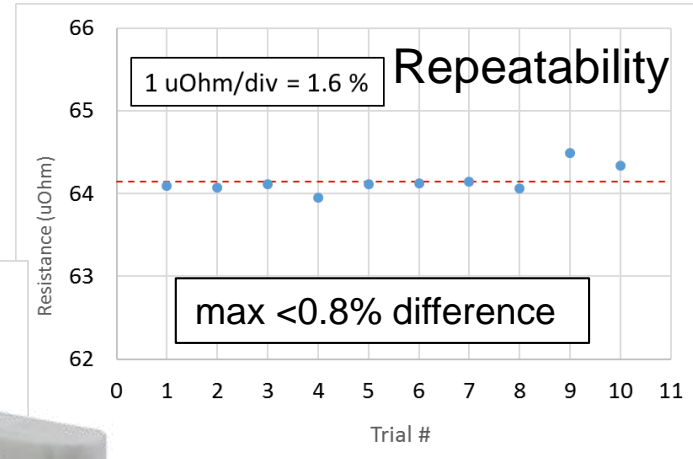
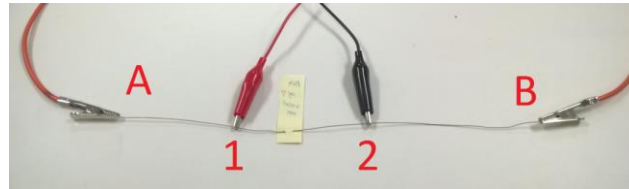
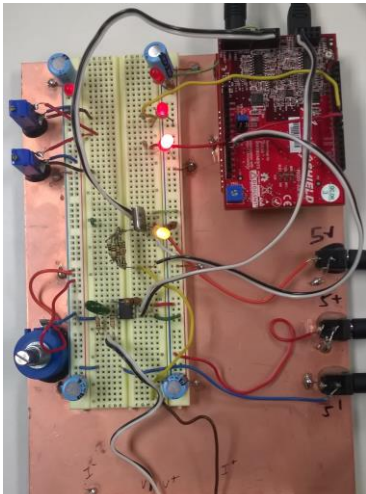
5 different trace widths to extract R_{sheet} and delta W

$$\frac{1}{R} = G = \frac{1}{R_{\square} \cdot \text{len}} (w + \Delta w) = mw + b$$

$$G = m \left(w + \frac{b}{m} \right); R_{\square} = \frac{1}{m \cdot \text{len}}; \Delta w = \frac{b}{m}$$

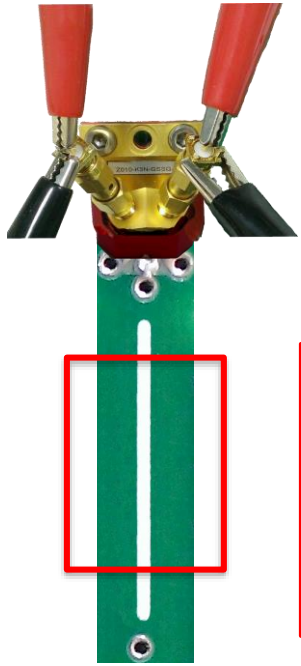


DC measurement with precision μOhm -meter



JAN 31-FEB 2, 2017

Extraction of R_{sheet} with DC measurement



$$G = m \left(w + \frac{b}{m} \right)$$

$$R_{\square} = \frac{1}{m \cdot len}; \Delta w = \frac{b}{m}$$

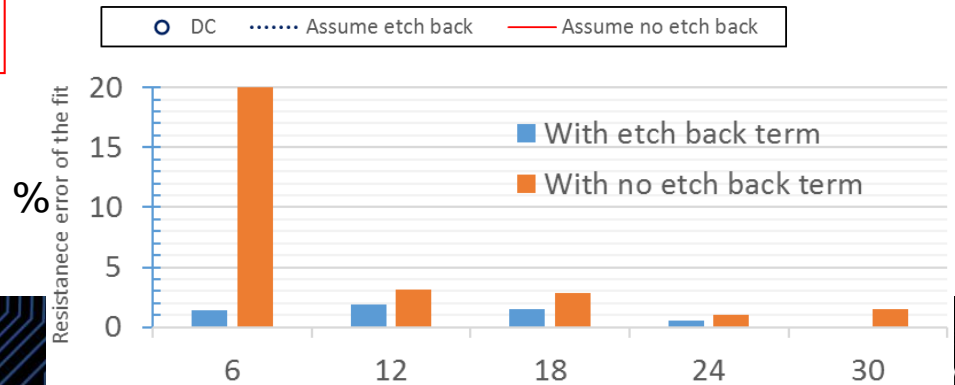
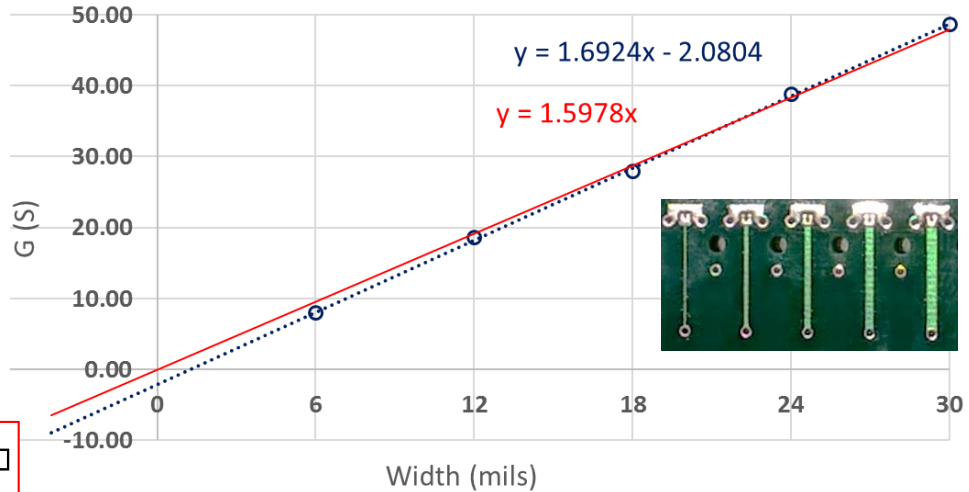
DC mOhm
1 in
125.61
53.80
35.76
25.81
20.55

$$R_{\square} = 0.591 \text{ m}\Omega / \square$$

$$\Delta w = -1.23 \text{ mils}$$

Rule of thumb:

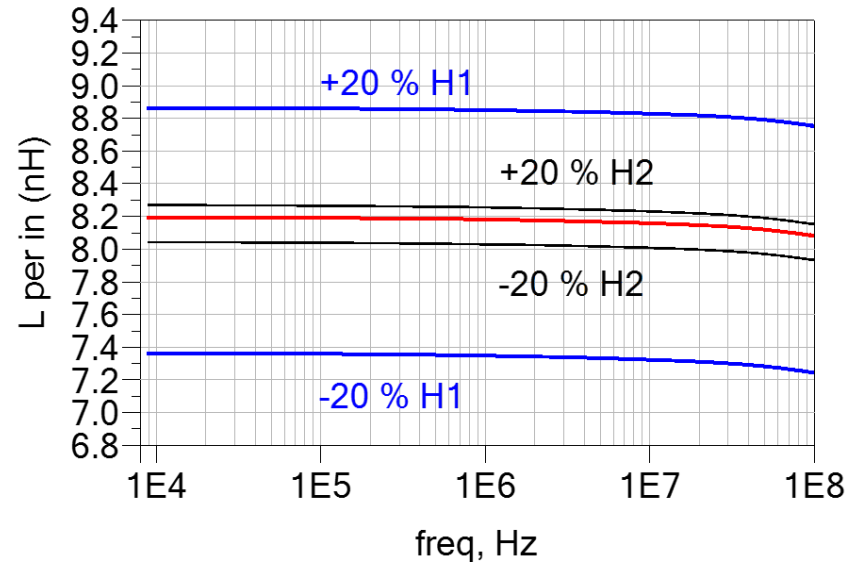
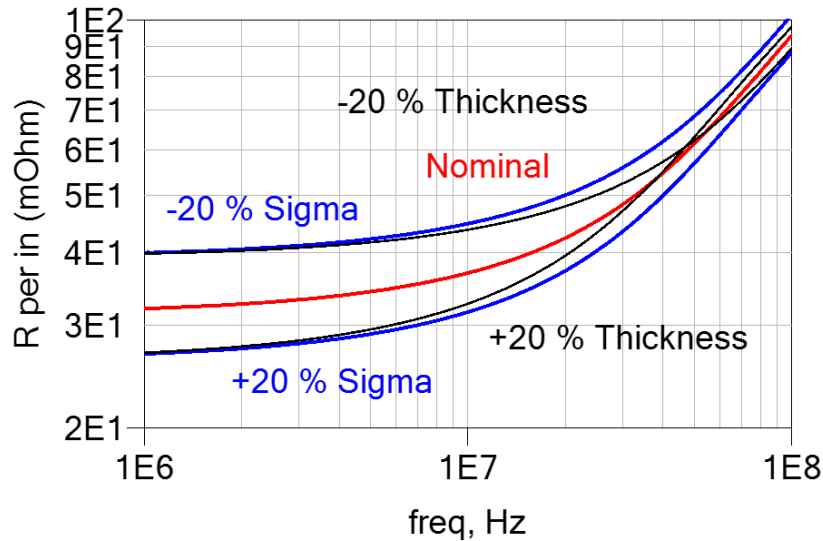
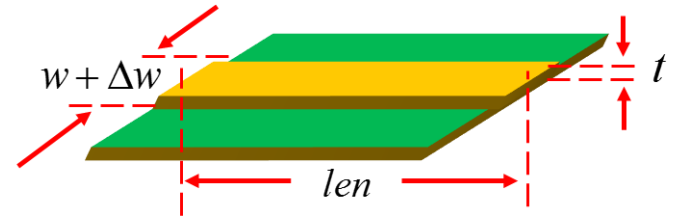
$R_{sheet} = 0.5 \text{ m}\Omega/\text{sq}$ for 1 oz copper



Reducing number of variables: divide and conquer

Variables: Sigma, T and H1.

$$R_{\square} = \frac{1}{\sigma t}$$



Road to R(f) & L(f)

Structures:

- Shorted transmission line
- 2X-thru

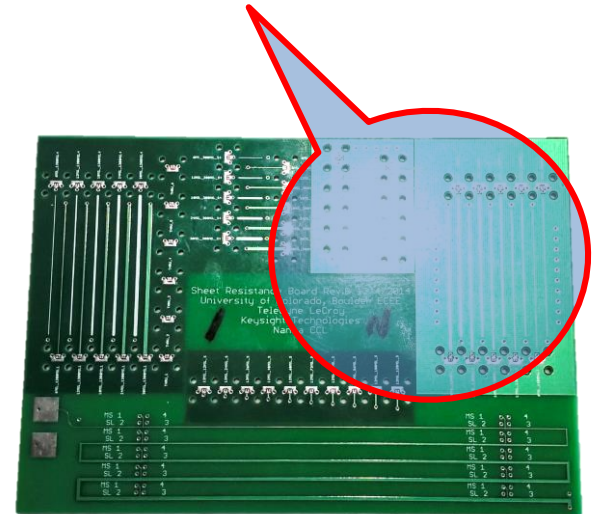
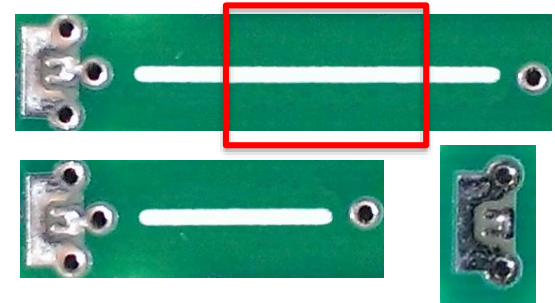
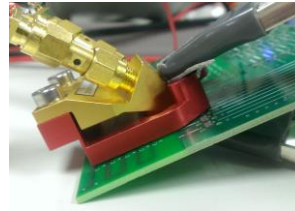
Measurement:

- S-parameter with 2 port technique
- What do we expect?

Data Process:

1. De-embedding and converting S-parameter to Zin
2. Extracting R(f) and L(f) from Zin
3. Taking the difference between two lengths
4. Fitting, sigma, T and H1 to the curves

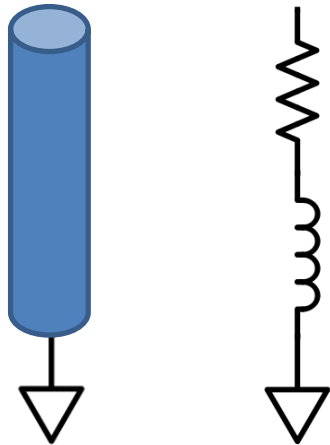
SET2DIL Footprint



Low frequency behavior: Input impedance of shorted tline and the 2 port technique

At low frequencies, the input impedance of a transmission line is:

$$\tilde{Z}_{in} \Rightarrow R_{Len}(f) + j\omega L_{Len}(f)$$

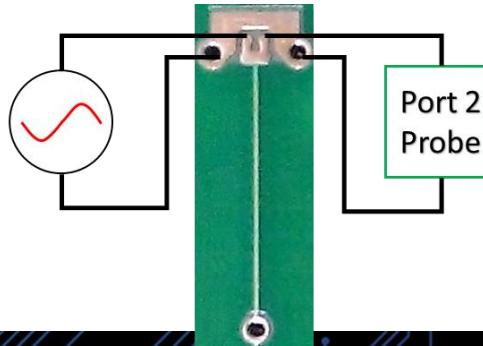


1 port measurement with estimated DC sheet resistance:
 $R_{DC}=15 \text{ mOhm}$

$$S_{11} = \frac{R_{DC} - 50}{R_{DC} + 50} = -0.005 \text{ dB}$$

Sensitive to Contact resistance > 15 mOhm

2 port technique for ultra low impedance measurement:

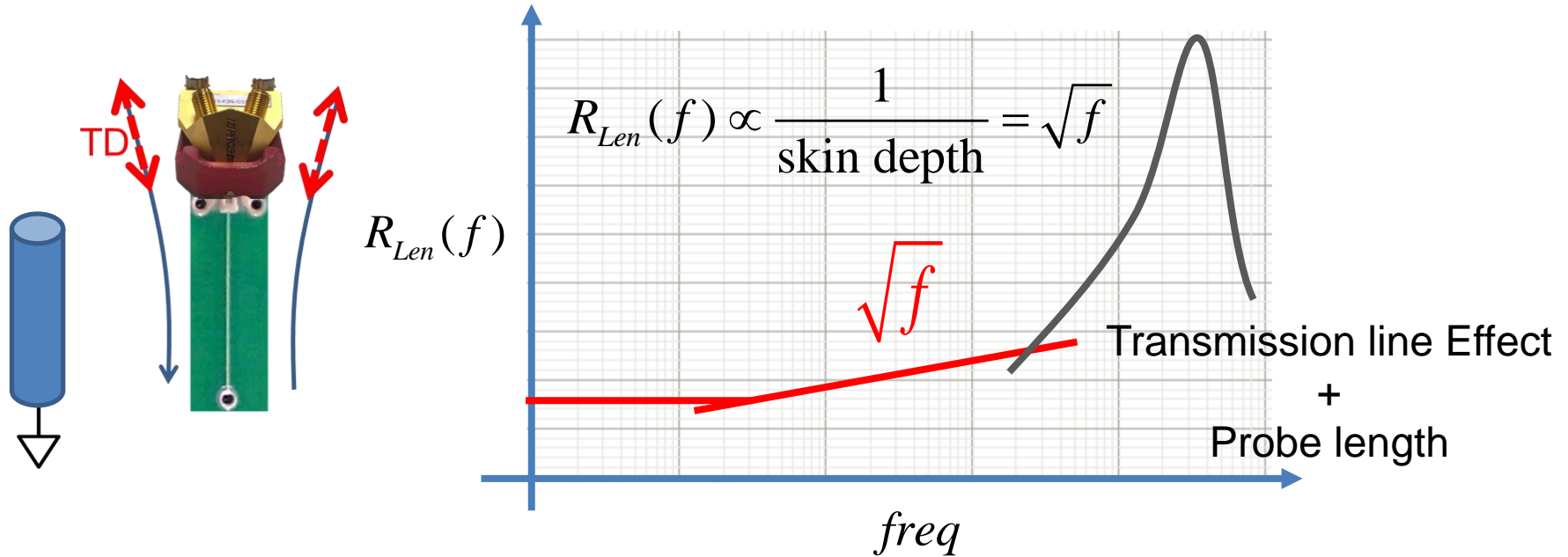


$$\tilde{Z}_{in} = 25 \frac{\tilde{S}_{21}}{1 - \tilde{S}_{21}} \Rightarrow \tilde{S}_{21} = \frac{\tilde{Z}_{in}}{25 + \tilde{Z}_{in}}$$

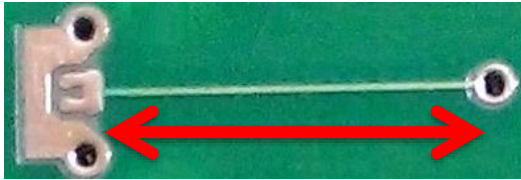
$$|S_{21}| = -64 \text{ dB}$$

Not sensitive to contact resistance!

Applying Rule #9: Expected $R_{Len}(f)$ behavior and identifying artifacts



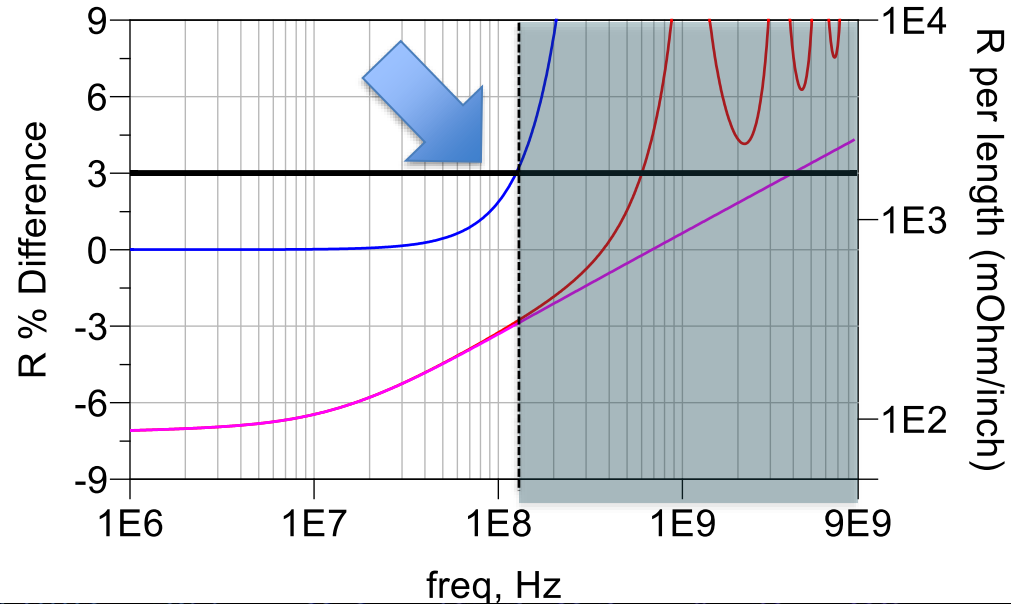
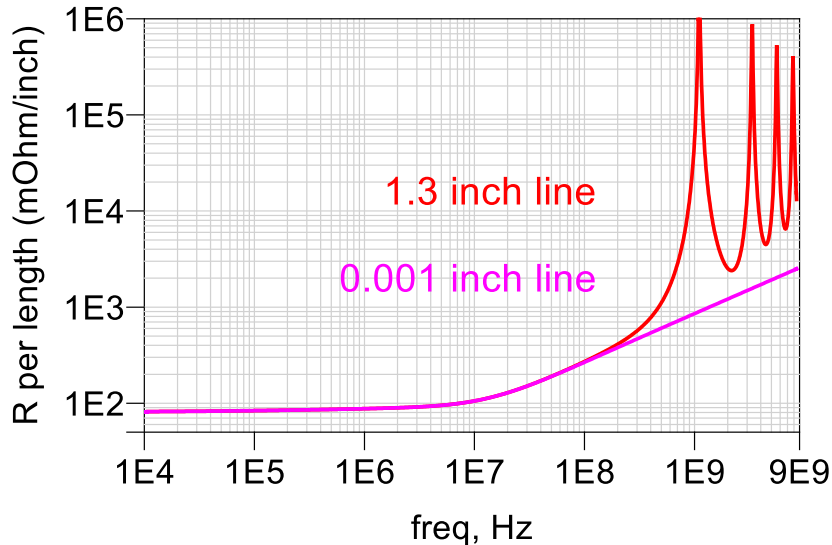
Artifact #1: Transmission line effect in R per len curve



Limiting factor: DUT is 1.3 inch.

At what frequency is measured data Tline effect free?

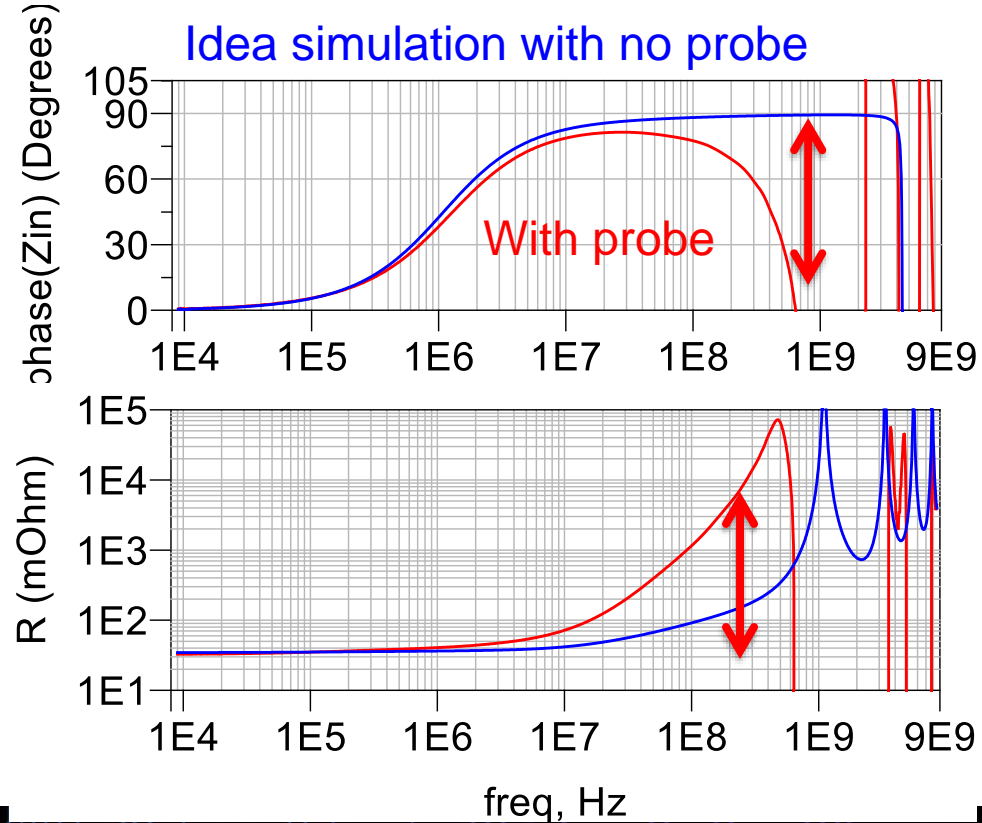
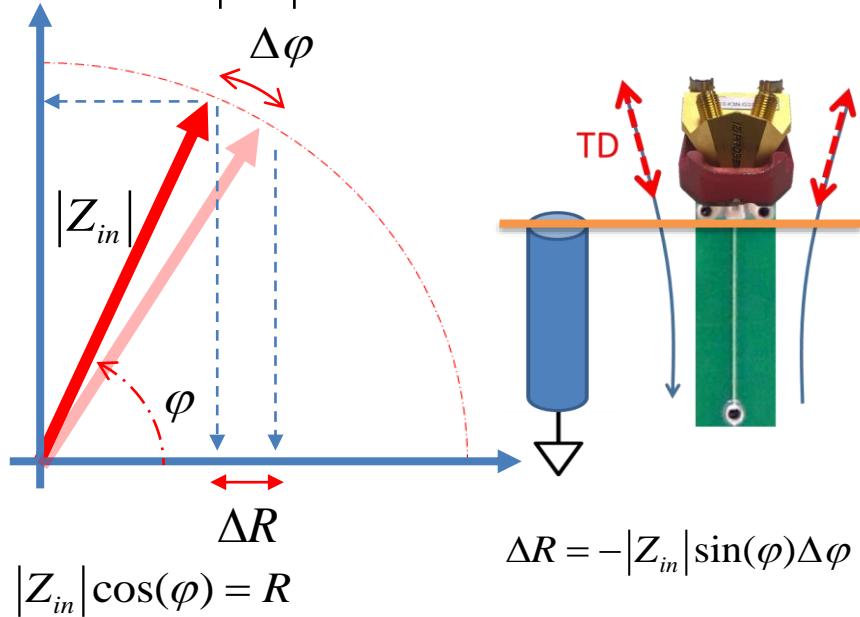
3% Resistance difference at 150 MHz



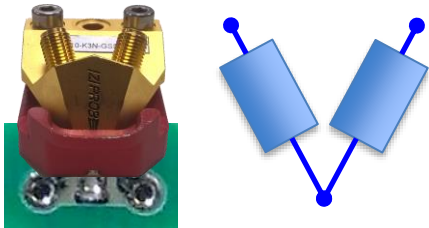
Artifact #2 phase introduced by probe length

$$|\tilde{Z}_{in}| e^{j\varphi} \approx 25 \cdot |S_{21}| e^{j\theta_{21}}$$

$$|\tilde{Z}_{in}| e^{j\varphi} = R_{Len}(f) + j\omega L_{Len}(f)$$



Variation in nominally identical thru

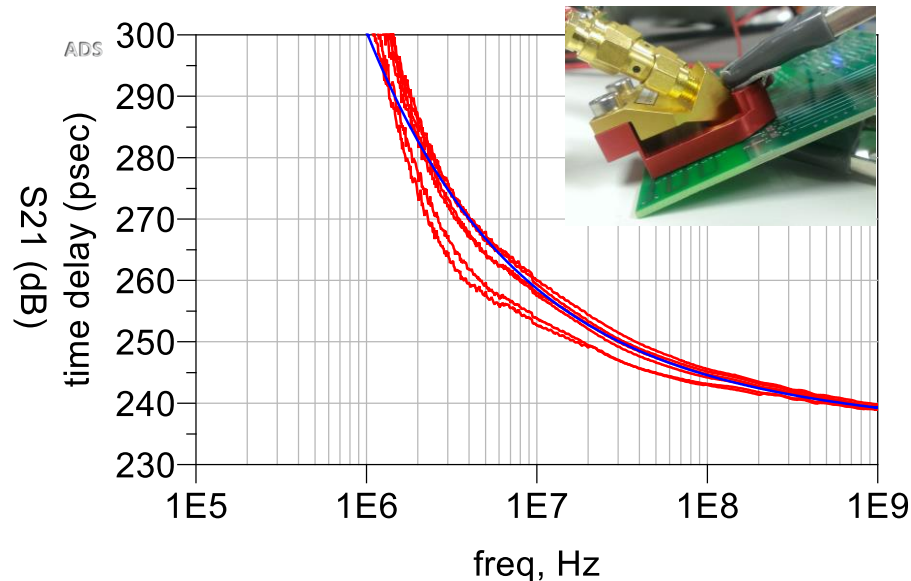
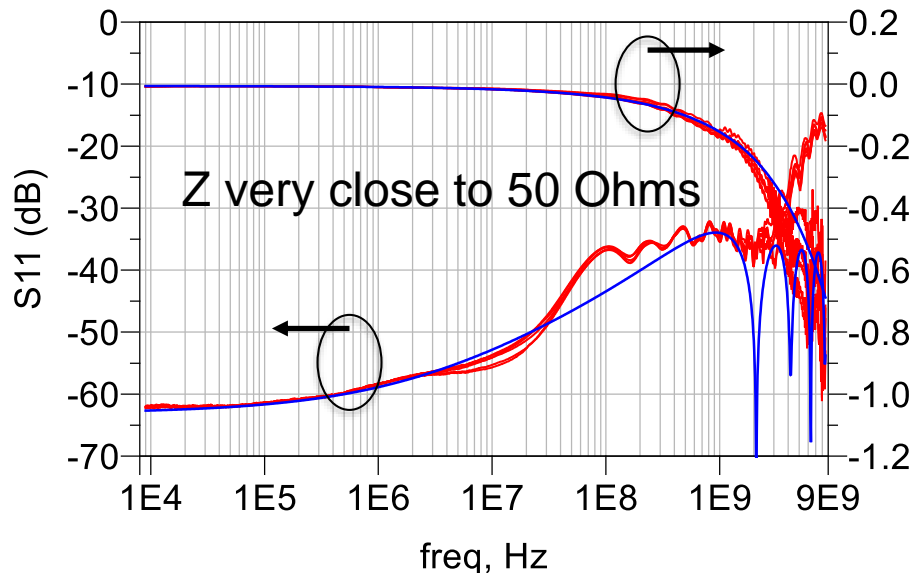


Nominal six same thru

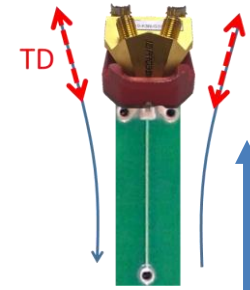


Model of fixture built and simulated in ADS

Estimated probe delay:
2 inches @ 8 inch/nsec
~250 psec



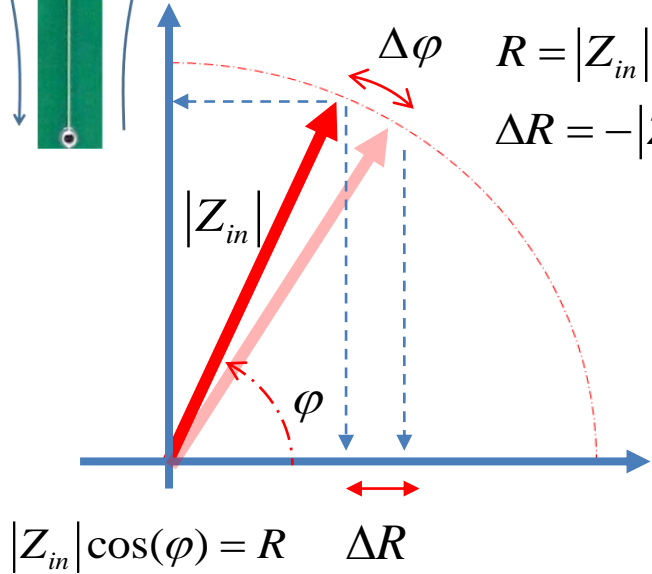
For a given Time Delay, delta R increases with frequency



$$|\tilde{Z}_{in}| e^{j\varphi} = R_{Len}(f) + j\omega L_{Len}(f)$$

$$R = |Z_{in}| \cos(\varphi)$$

$$\Delta R = -|Z_{in}| \sin(\varphi) \Delta\varphi$$



$$\frac{\Delta R}{R} = -\tan(\varphi) \Delta\varphi; \Delta\varphi = \Delta TD \cdot 2\pi f$$

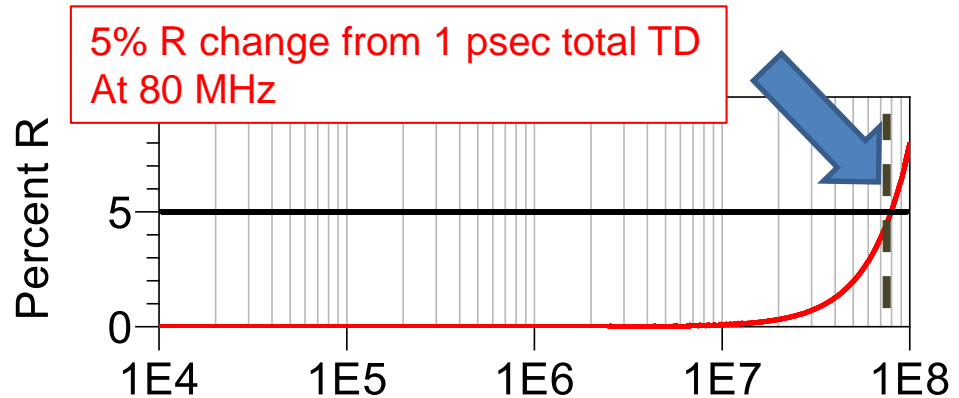
$$\frac{\Delta R}{R} = \frac{\omega L}{R} \Delta TD \cdot 2\pi f$$

Estimated DC sheet resistance: 15 mOhm

Estimated Inductance strip line : 5 nH/in * 0.3 inch -> 1.5nH

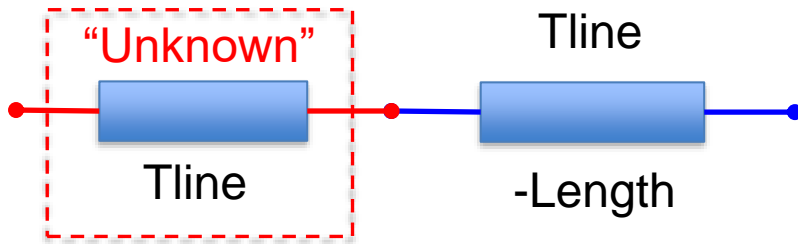
Delta time delay (total) = 1 psec Freq = 100MHz

R %change = 4%



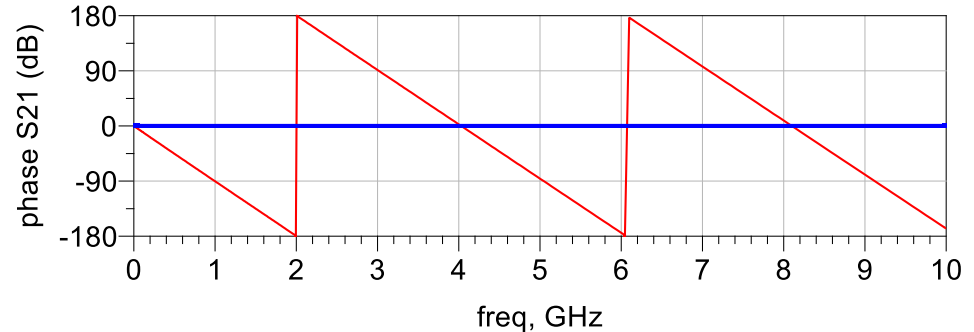
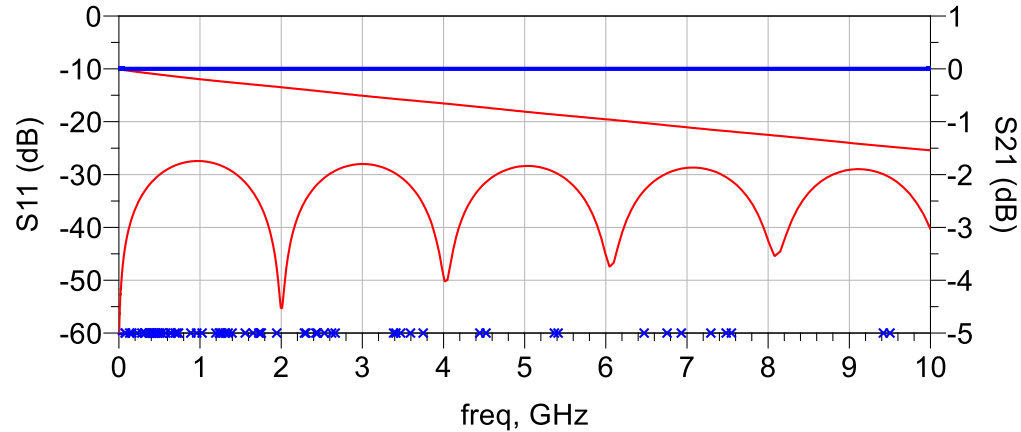
A new flexible deembedding technique: negative length

Virtual prototype

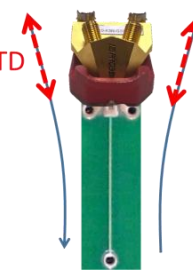


52 Ohm, 1.5 inch, FR4

Parameter	After De-embedding
S_{11}	No ripples
S_{21}	Flat
Phase S_{21}	0 degree



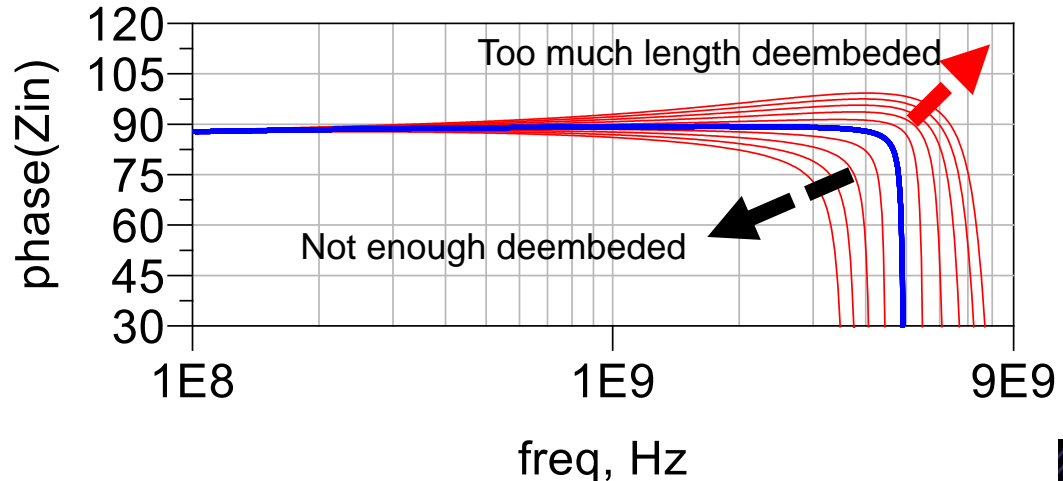
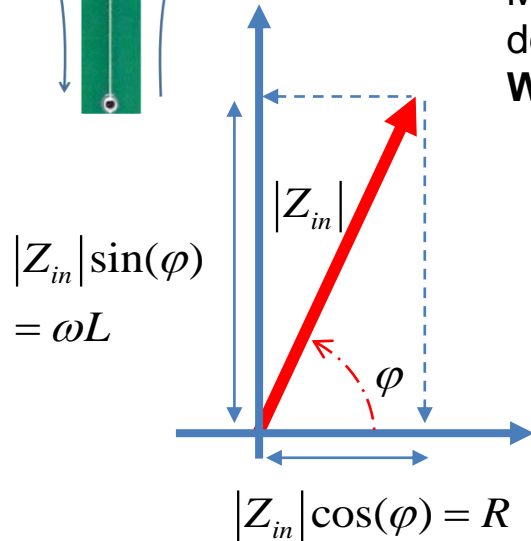
How do we know if we deembedded enough/too much?



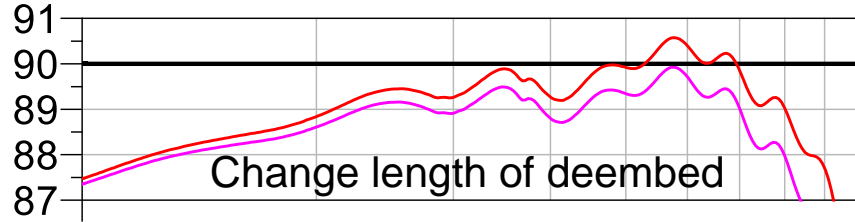
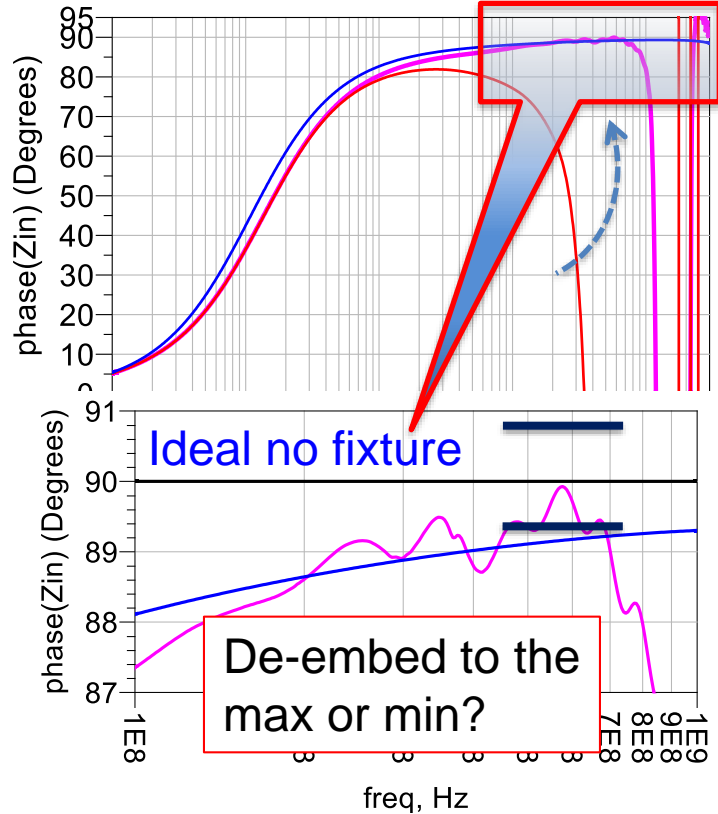
$$\tilde{Z}_{in} = 25 \frac{\tilde{S}_{21}}{1 - \tilde{S}_{21}} \Rightarrow |\tilde{Z}_{in}| = 25 \frac{|\tilde{S}_{21}|}{\sqrt{1 - 2|\tilde{S}_{21}|\cos(\theta_{21}) + |\tilde{S}_{21}|^2}} \quad \varphi = \angle \tilde{Z}_{in} = \tan^{-1} \left(\frac{\sin(\theta_{21})}{\cos(\theta_{21}) - |\tilde{S}_{21}|} \right)$$

Mathematically, $-90 < \varphi < 90$ because $-90 < \arctan < 90$, but we are dealing with numerical simulations when de-embedding.

We need to make sure de-embedded result is physical.



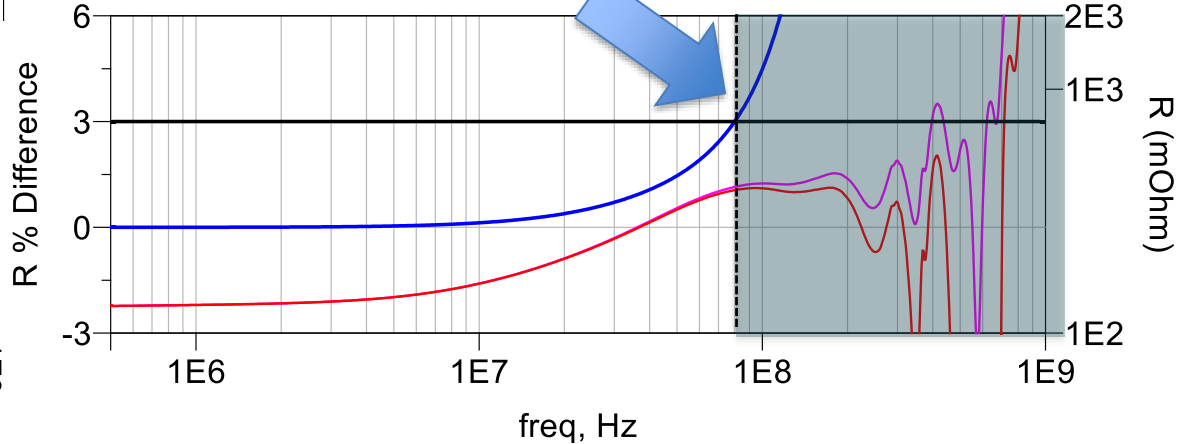
Hidden Artifact #3: noise in phase after deembedding



~1 psec
Numerical
noise

How much % difference is in R(f)?

3% at 80 MHz



Review of Measurement procedure

- 2 port measurement

- Long structure
- Short structure



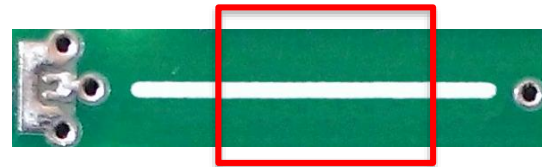
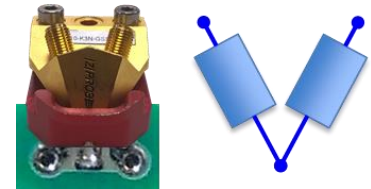
$$R_{Len}(f) = \frac{\text{real}(\tilde{Z}_{in})}{len}$$

$$L_{Len}(f) = \frac{\text{imag}(\tilde{Z}_{in})}{\omega} \frac{1}{len}$$

- Process

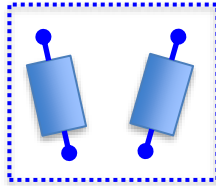
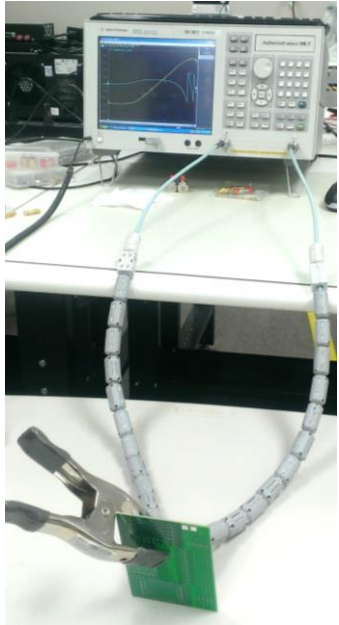
- Convert to Z_{in} to $R(f)$ and $L(f)$.
- De-embed both structures with negative length transmission.
- Take the difference between the $R(f)$, $L(f)$ results from long structure and short.

$$\tilde{Z}_{in} = 25 \frac{\tilde{S}_{21}}{1 - \tilde{S}_{21}}$$

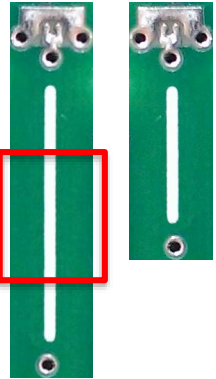


Deembedded RF Measurement and DC consistency test

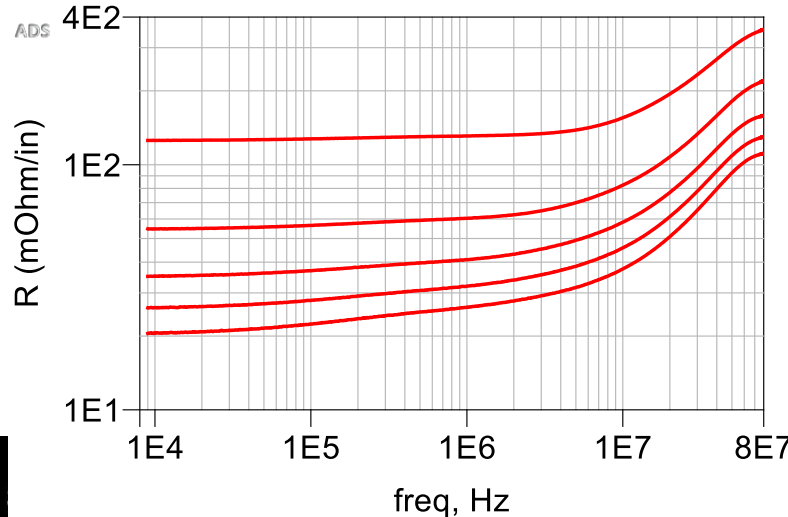
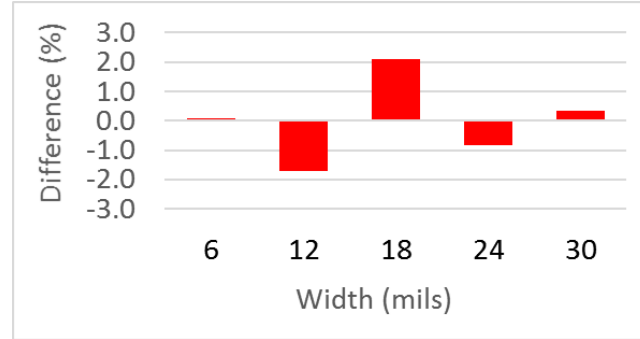
Keysight E5071C
9 kHz-8.5 GHz



R_{long} R_{short}



Resistance per inch (mOhm)		
w (mil)	DC	RF
6	125.6	125.5
12	53.8	54.7
18	35.8	35.0
24	25.8	26.0
30	20.6	20.5



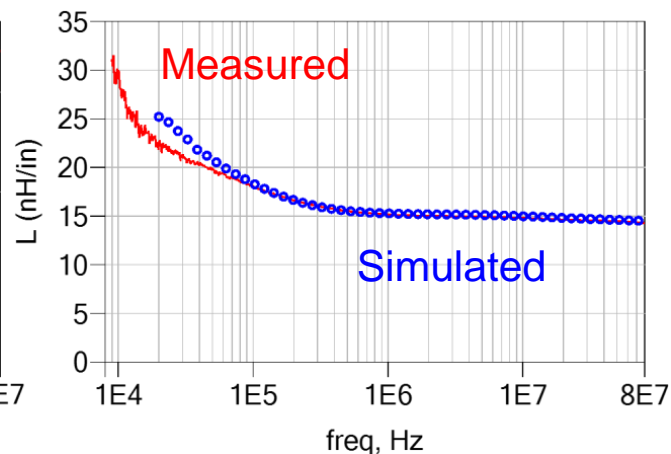
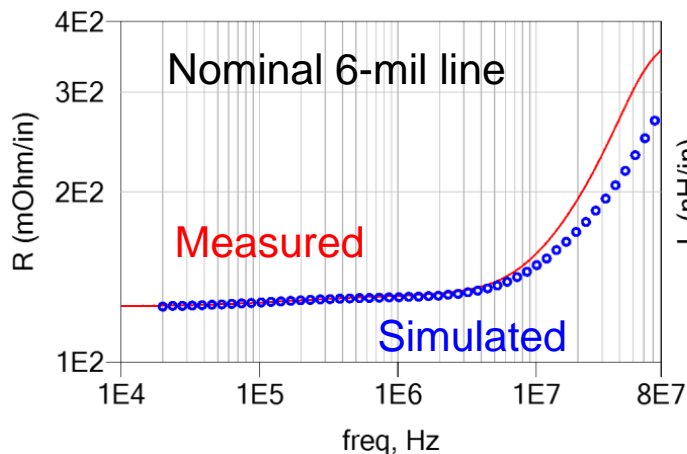
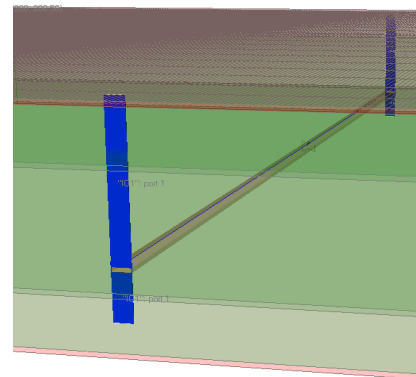
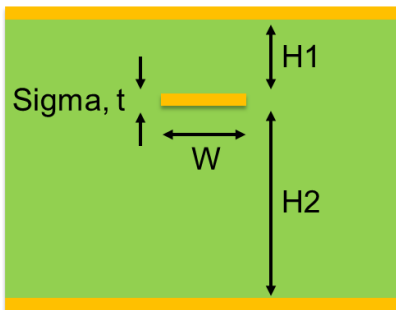
	R sheet	delta W
DC	0.591	-1.23
RF	0.589	-1.26

Difference from DC:
 R_{sheet} : 0.3%,
 Delta W: 2.7%



Fitting to the T With Simbeor

Param.	Vendor value	Input to Simbeor
Dk	4.3	4.3
Df	0.0165	0.0165
H1 (mil)	14.1	12.9
H2 (mil)	42.1	40.9
W (mil)	6	4.77
T (mil)	1.2	1.2
σ (S/m)	5.8e7	5.6e7



$$R_{\square} = 0.591 \text{ m}\Omega / \square$$

$$\Delta w = -1.23 \text{ mils}$$

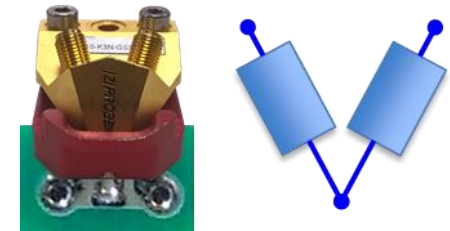
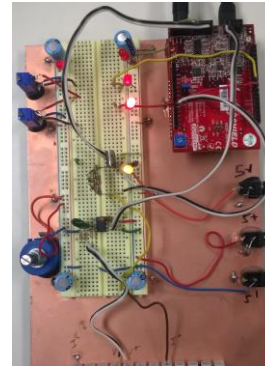
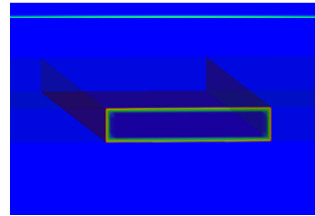
$$\sigma = \frac{1}{R_{\square} t}$$



Summary

- Demonstrated skin depth and current distribution in a trace.
- Used 5x line technique to extract etch-back and sheet resistance.
- Built a low cost precision micro-Ohm meter for low level measurement.
- Used SET2DIL test pattern in designing test patterns.
- Performed 2-port technique for ultra-low resistance RF measurement.
- Achieved DC and RF resistance correlation within 3%.
- Illustrated the impact of probe length uncertainty.
- Introduced a new flexible negative length de-embedding technique.

8 GHz



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